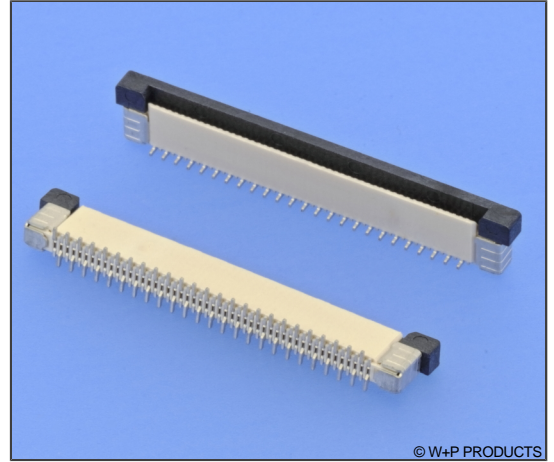


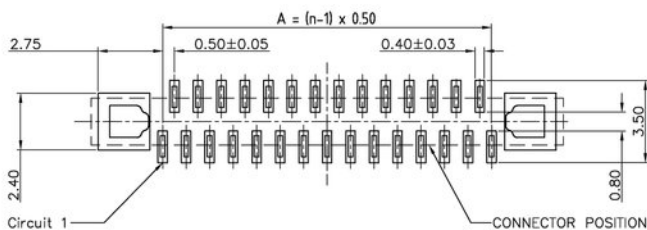
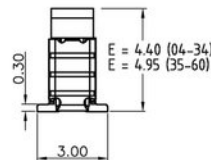
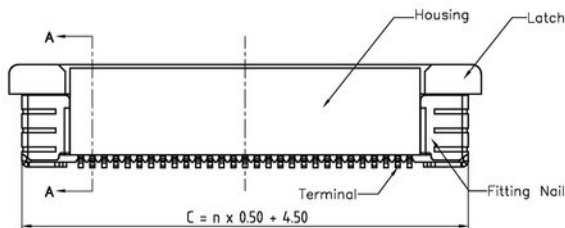
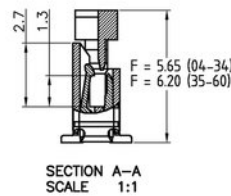
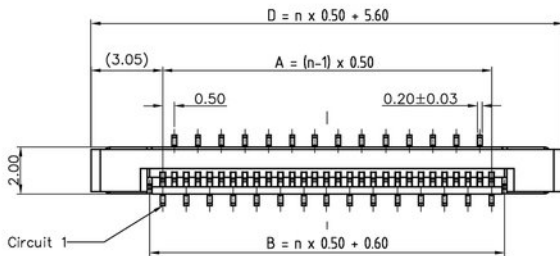
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0, halogenfrei <i>Thermoplastic, rated UL94 V-0, halogen free</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktfläche <i>Contact Surface</i>	Zinn über Nickel <i>Tin plated over nickel</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 40 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 500 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	200 V AC
Nennspannung <i>Voltage Rating</i>	50 V AC
Nennstrom <i>Current Rating</i>	0,4 A
Temperaturbereich <i>Temperature Range</i>	-25 °C ... +85 °C
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

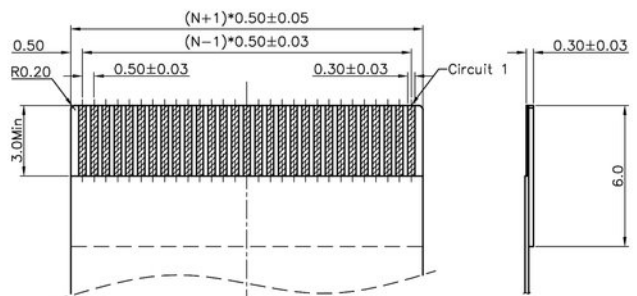


© W+P PRODUCTS

Passende Flex-Kabel:
Compatible Flex Cables:
599



RECOMMENDED P.C.B. PATTERN LAYOUT



RECOMMENDED FPC/FFC DIMENSION

Series

5582

Contacts*

34

04/06/08-16/18/
20/22/24/26/28/
30/32-34/36/40/
45/50/54/60

Package

TR

TR Tape & Reel
Tape & Reel

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	217 °C
Duration above T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

